

"Express Mail" mailing label number EL 562 416 792 US

Date of Deposit: November 8, 2000

cc
1160
#21
pre G

Our Case No. 7103/30-2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Homayoun Talieh et al.

Serial No. 08/853,323

Filing Date: May 8, 1997

For LINEAR POLISHER AND
METHOD FOR SEMICONDUCTOR
WAFER PLANARIZATION

Examiner: G. Nguyen

Group Art Unit No. 3723

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated May 8, 2000 please enter the following amendment and consider the following remarks:

IN THE CLAIMS:

Please amend claims 32, 34, 36-38, and 40 as follows:

32. (Five Times Amended) A polishing pad assembly for polishing a semiconductor wafer, said assembly comprising:

a belt forming a closed loop;

at least one non-[fixed] abrasive [chemical mechanical planarization] polishing pad mounted on the belt, the non-[fixed] abrasive [chemical mechanical planarization] polishing pad configured to receive a polishing slurry suitable for use in chemical mechanical planarization of the semiconductor wafer, wherein the non-[fixed] abrasive [chemical mechanical

RECEIVED
NOV 15 2000
TC 3700 MAIL ROOM